IPC ASSOCIATION OF ELECTRONICS	CONNECTING © Copyrinternation	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This level	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1						Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information					
upplier l	Information																
Company name* Company unique ID				ique ID	Uniqu			Unique ID Authority					Response Date*				
nsemi								I					2023-06-08				
Contact Name				Title - Contact			P	Phone - Contact*					Email - Contact*				
?roduct-En	ıv-Stewards			Product Enviro Compliance			ľ	NA					Product-Env-Stewards@onsemi.com				
Authorized Representative*				Title - Representative			P	Phone - Representative*					Email - Representative*				
Product-Env-Stewards				Product Enviro Compliance			ľ	NA					Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Mfr Item N	em Number Mfr Item Name				Effective Date	e Versio	on :	Manufacturing Site		V	Weight*	UOM	Ţ	Init Type
				OR NA; Two phase of the thod (no speed cont		2023-06-08	РНМ			1	30.0	mg	E	ach			
Ianufact	turing Process	Information															
Т	Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 MS		-STD-020 MSL Rati	ng	Peak Process Body Tem		Temperatu	perature Max Time at Peak T		Temperatu	ure Nur	mber of Reflov	v Cycles	
contains Bi		CU	CU Alloy 3		3		260	260 C		30 seco		second	ds 3				
omments																	
LIENTIO	N: MSL 3 Rated it	tem requires Bak	e and Dr	y Pack (after	r electrical test)												
or more in	formation regardin	ng material comp	osition p	lease refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).												
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier is liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.												
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.96	mg	Supplier	Silicon (Si)	7440-21-3		4.9416	mg
			Supplier	Polyimide	Proprietary Data		0.0184	mg
Die Attach	0.4	mg	Supplier	Silver (Ag)	7440-22-4		0.306	mg
			Supplier	Epoxy resins	129915-35-1		0.094	mg
Lead Frame	15.4	mg	Supplier	Zinc (Zn)	7440-66-6		0.0293	mg
			Supplier	Iron (Fe)	7439-89-6		0.3989	mg
			Supplier	Copper (Cu)	7440-50-8		14.9503	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0216	mg
Mold Compound-Black	107.19	mg		Epoxy Phenol Resin	proprietary data		11.7909	mg
			Supplier	Carbon Black (C)	1333-86-4		0.536	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		48.7715	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		46.0917	mg
Plating	1.72	mg	В	Bismuth (Bi)	7440-69-9		0.0103	mg
			Supplier	Tin (Sn)	7440-31-5		1.7097	mg
Wire Bond - Au	0.33	mg	Supplier	Gold (Au)	7440-57-5		0.33	mg